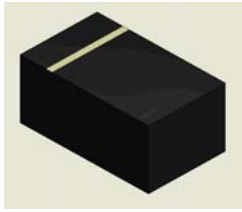




CDB0230QRM

200mA 30V

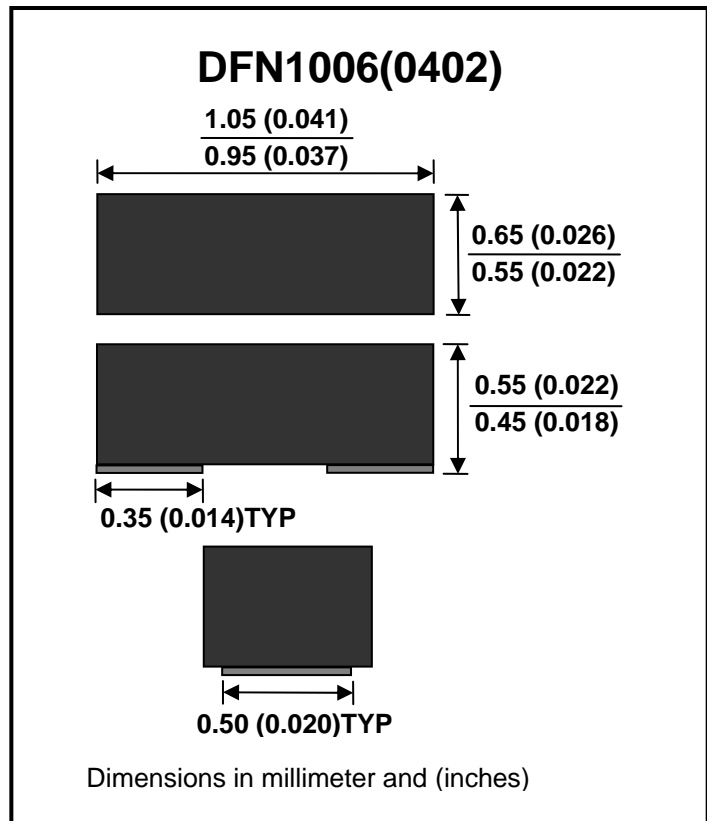


Features

- Low reverse current.
- Designed for mounting on small surface.
- Extremely thin / leadless package.
- Majority carrier conduction.
- Pb free version, RoHS compliant, and Halogen free

Mechanical Characteristics

- Case: DFN1006(0402) mold package
- Terminals: Sn/Au plated, solderable per MIL-STD-750, method 2026.
- Marking code: cathode band & BB
- Mounting position: Any.
- Weight: 0.001 gram(approx.)



Maximum Rating And Electrical Characteristics (at Ta=25°C unless otherwise noted)

Parameter	Condition	Symbol	Min	Typ	Max	Unit
Repetitive peak reverse voltage		V _{RRM}			35	V
Reverse voltage		V _R			30	V
Average forward current		I _o			200	mA
Forward current surge peak	8.3ms single half sine-wave superimposed on rate load(JEDEC method)	I _{FSM}			1	A
Power Dissipation		P _D			125	mW
Storage/Operation temperature		T _{Sgt}	-40		+125	°C
Junction temperature		T _J			+125	°C
Forward voltage	I _F =200mA	V _F			0.6	V
Reverse current	V _R =10V	I _R			1	uA



Typical Characteristics

Fig.1-Forward characteristics

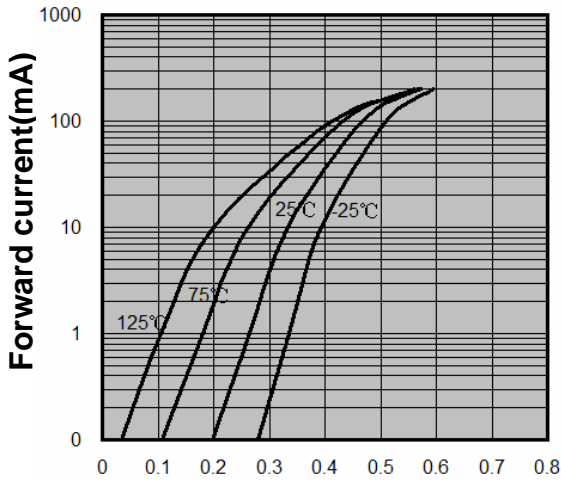


Fig.2-Reverse characteristics

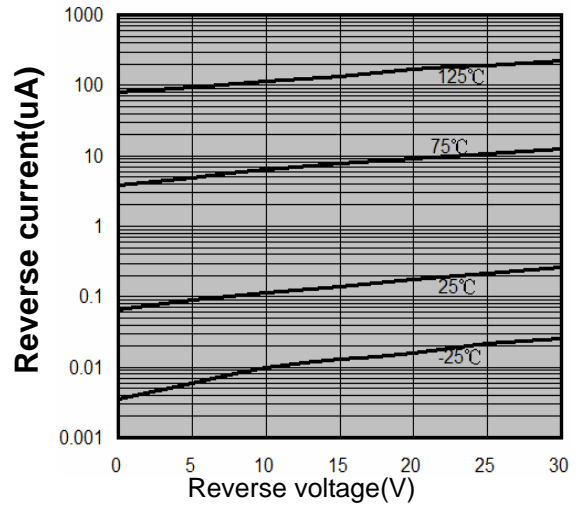


Fig. 3 - Capacitance between terminals characteristics

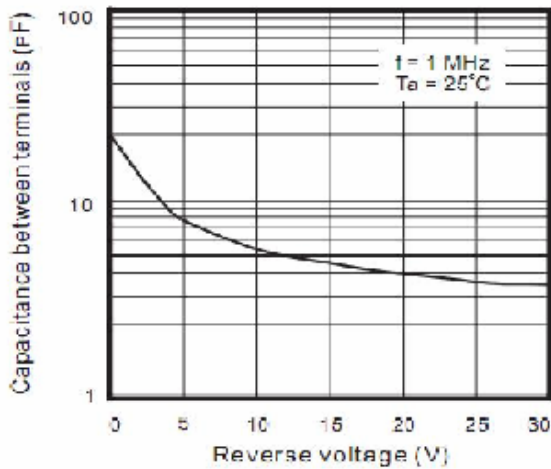


Fig.4 - Current derating curve

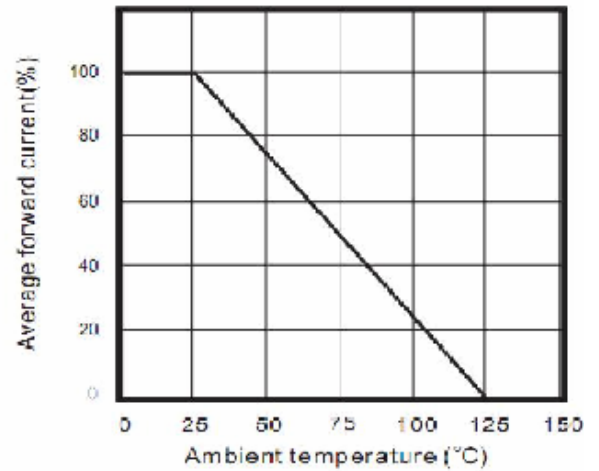


Fig. 5 - VF Dispersion map

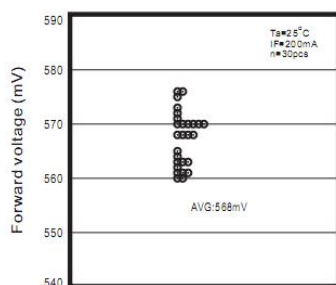


Fig. 6 - IR Dispersion map

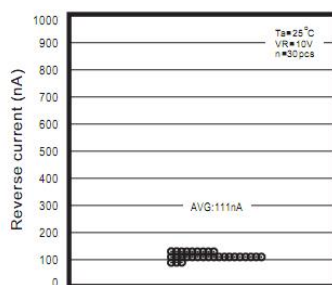
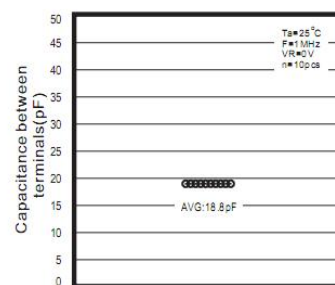
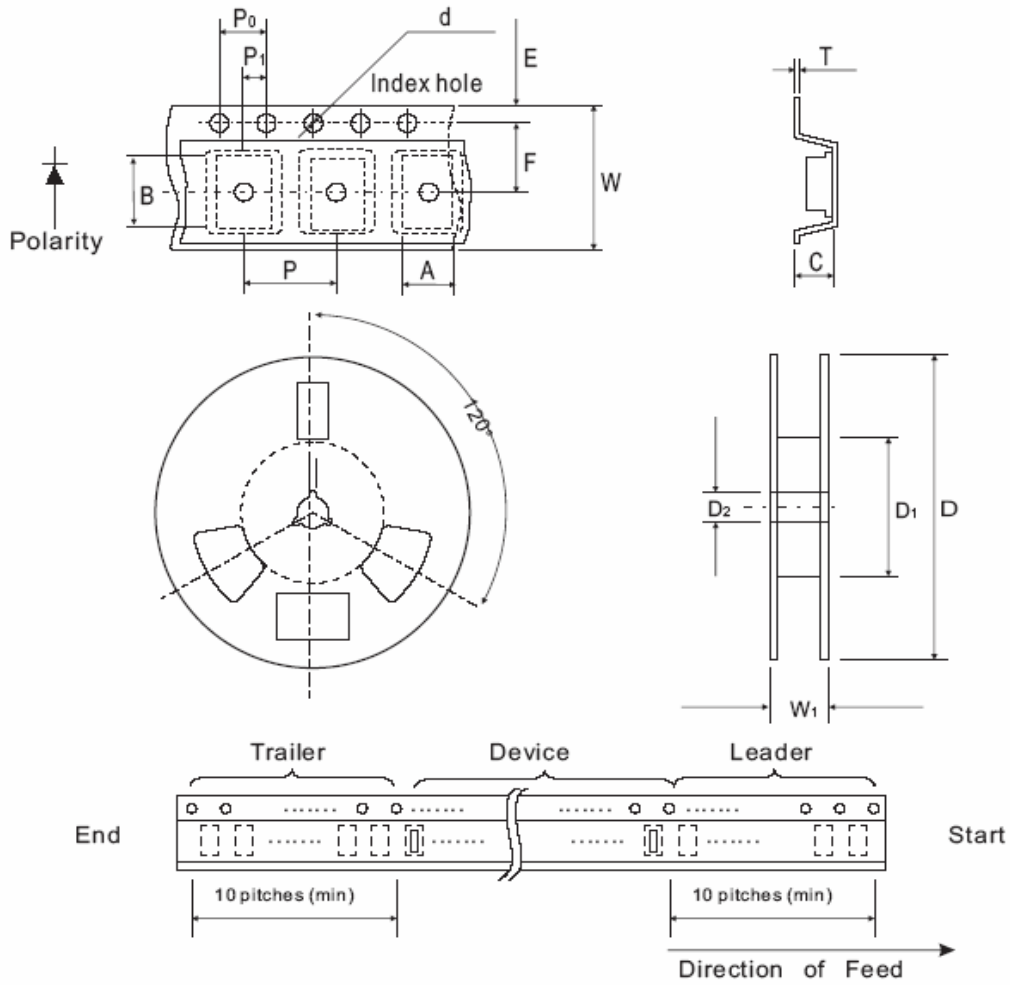


Fig. 7 - CT Dispersion map





Packing Specification



Tape & Reel Dimensions

Package	Unit	A	B	C	d	D
DFN1006	mm	0.67±0.10	1.12±0.10	0.60±0.10	1.50±0.10	178±1
	inch	0.026±0.004	0.044±0.004	0.024±0.004	0.060±0.004	7.008±0.04

Package	Unit	D1	D2	E	F	P
DFN1006	mm	60MIN	13.0±0.20	1.75±0.10	3.5±0.10	4.0±0.10
	inch	2.362MIN	0.512±0.008	0.069±0.004	0.138±0.004	0.157±0.004

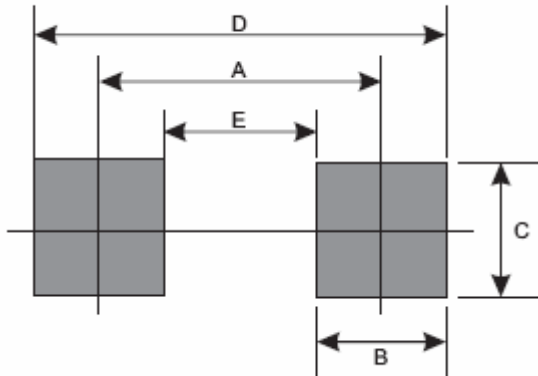
Package	Unit	P0	P1	T	W	W1
DFN1006	mm	4.0±0.10	2.0±0.10	0.22±0.03	8.0±0.10	10.5±0.5
	inch	0.157±0.004	0.079±0.004	0.009±0.002	0.315±0.004	0.413±0.02



Standard Package

Package	Reel Size	Qty/Reel
DFN1006	7"	5,000 pcs

Recommended Soldering Footprint



Reflow Soldering

Product Size	Dimension/ mm				
	A	B	C	D	E
DFN1006	0.750	0.500	0.700	1.250	0.250
	0.030"	0.020"	0.028"	0.049"	0.010"

Marking Code

Part Number	Marking Code
CDB0230QRM	BB



Disclaimers

These products are not designed for use in applications where any failure or malfunction may result in personal injury, death or severe property or environmental damage such as medical, military, aircraft, space or life support equipments.

单击下面可查看定价，库存，交付和生命周期等信息

[>>LIZ\(丽智\)](#)